

adjustable.

49. An apparatus according to claim 44, wherein said base is provided with an overflow collar.

50. An apparatus according to claim 49, wherein said overflow collar is provided with at least one inwardly directed nozzle.

51. An apparatus according to claim 44, wherein a tank is provided that surrounds said base.

52. An apparatus according to claim 33, wherein a substrate carrier is provided for holding a substrate, and wherein a device is provided for conducting a fluid onto an outer side of said substrate carrier.

53. An apparatus according to claim 52, wherein said device is disposed on said substrate carrier.

54. A method of processing substrates, including the steps of:
providing at least one first nozzle, and a nozzle plate disposed parallel to a substrate, wherein said at least one first nozzle is disposed essentially centrally relative to said substrate and to said nozzle plate;

conducting a fluid, via said at least one first nozzle, at a right angle onto a substrate surface that is to be treated so that fluid striking said substrate is deflected into a radial flow between said substrate and said nozzle plate;

providing a plurality of second nozzles disposed in said nozzle plate at an angle of less than 90°, wherein said second nozzles are separately controllable from said at least one first nozzle;

conducting a fluid, via said at least one first nozzle and transverse to said radial flow, onto said substrate surface that is to be treated, wherein fluid is

simultaneously conducted onto said substrate surface by said first and second nozzles; and

wherein said second nozzles are distributed over said nozzle plate in such a way that said radial flow is deflected into a spirally outwardly extending flow.

55. A method according to claim 54, wherein said fluid is conducted via said second nozzles onto said surface that is to be treated in essentially a peripheral direction of said substrate.

56. A method according to claim 54, wherein said fluid is conducted onto said substrate surface that is to be treated via said second nozzles at an angle of 45°.

57. A method according to claim 54, wherein fluid is conducted onto said substrate surface that is to be treated via said first and second nozzles at different pressures.

58. A method according to claim 54, wherein different fluids are conducted onto said substrate surface that is to be treated via said first and second nozzles.

59. A method according to claim 54, wherein a rinsing fluid is conducted onto said substrate surface that is to be treated via said at least one first nozzle.

60. A method according to claim 54, wherein a vacuum is applied to said at least one first nozzle.

61. A method according to claim 54, wherein a gas is conducted onto the substrate surface that is to be treated via said second nozzles.

62. A method according to claim 54, wherein an overflow collar having at least one further nozzle is provided, and wherein a fluid is conducted onto an outer surface of a substrate carrier that carries a substrate via said at least one further

nozzle.

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